

wherein the package can be a multi-chip module (MCM), including multiple integral windows and multiple microelectronic devices in a two-dimensional array.

Fig. 9 shows a schematic cross-section side view of another example of a microelectronic package for housing at least one microelectronic device according to the present invention, wherein the window further comprises a lens for optically transforming light passing through the window.

Fig. 10A shows a schematic cross-section side view of another example of a microelectronic package for housing a microelectronic device, according to the present invention.

Fig. 10B shows a schematic cross-section side view of another example of a microelectronic package for housing a microelectronic device, according to the present invention.

Fig. 10C shows a schematic cross-section side view of another example of a microelectronic package for housing a microelectronic device, according to the present invention.

Fig. 10D shows a schematic cross-section side view of another example of a microelectronic package for housing a microelectronic device, according to the present invention.

~~Fig. 11 shows a schematic cross section side view of another example of a microelectronic package for housing a microelectronic device, according to the present invention.~~

Fig. 11 shows a schematic cross-section side view of another example of a package for housing a pair of back-to-back microelectronic devices, according to the present invention.

Fig. 12A shows a schematic cross-section side view of another example of a package for housing a pair of back-to-back microelectronic devices, according to the present invention.